

PDM: Rev:K

STATUS Released

Printed: Jul 31, 2006

PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
84500-002	YES	15u" (.38um) Au OVER Ni	SnPb
84500-002LF			SnAgCu LEAD FREE (7)(8)
84500-102	YES	30u" (.76um) Au OVER Ni	SnPb
84500-102LF			SnAgCu LEAD FREE (7)(8)
84500-202	YES	SEE MATED HEIGHT TABLE (BELOW).	SnPb
84500-202LF			SnAgCu LEAD FREE (7)(8)

NOTES:

(1.) MAT'L

HOUSING: LCP

CONTACT: COPPER ALLOY

PLATING

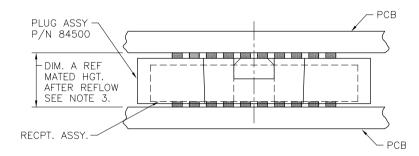
CONTACT: (SEE TABLE ON SHEET3)

SOLDER BALL: (SEE TABLE ON SHEET3)

EUTECTIC SnPb OR LEAD FREE

95.5Sn/4Aa/0.5Cu

- (2.) SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- (3.) MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- (4.) PLATING FOR INDICATED -2XX SERIES PART NOS. MEETS THE REQUIREMENTS OF NORTEL NPS25298-2 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).
- $(5.)\,\mathrm{PLATING}$ FOR INDICATED $-2\mathrm{XX}$ SERIES PART NOS. IS Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.
- (6.) KNIT LINE: SLIGHT VISIBLE MARKS (USUALLY A LINE) INDICATING THE DIRECTION AND MEETING POINT OF PLASTIC RESIN FLOW FRONTS TRAVELING AROUND ANY OBSTRUCTIONS TO THE RESIN FLOW VIA THE REQUIRED MOLD TOOLING.
- FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THERFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- (8.) THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION



MATED HEIGHT TABLE										
DIM. A	RECPT. ASSY. P/N	-2XX PLATING								
4.0	84501	SEE NOTE 4.								
5.5	84502	*								
8.0	84553	SEE NOTE 5.								

* 84502 NOT AVAILABLE IN TELCORDIA/NORTEL VERSION.

MATED HEIGHT AFTER REFLOW IS BASED ON Ø .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS scale: NONE

mat'l. code			surface / t		tolerance		projection		product family															
SEE NOTE 1.			ASME Y14.5 V ASME Y14.5				⊕-⊟			MEG-ARRAY														
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